

TruNanoTM processing of dielectric layers and barrier-rib on soda-lime glass substrate for PDP panel

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Abstract

We present a low temperature thermal process for the transparent dielectric layer, barrier rib, and white back dielectric layer on the soda-lime glass substrate of the PDP by the TruNanoTM processor in combination with a compositional modification to the conventional dielectric pastes. By this method the firing temperature can be lowered by more than 100°C.